



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2014-10-02
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	J79U*V069CAA	A	MU1A	2014-10-02
Amount	UoM	Unit type	ST ECOPACK Grade	
670.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	7.5,15.4,2.50	24	gull wing	
Comment	Package: SO 24 .30 TO JEDEC MS-013AD; MDF valid for STA020DJTR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	J79U*V069CAA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	2.727	mg	supplier	die	Silicon (Si)	7440-21-3		2.624	mg	962230	3916
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	1834	7
Die or Dies				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	1100	4
Die or Dies				supplier	metallization	Tungsten (W)	7440-33-7		0.016	mg	5867	24
Die or Dies				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.003	mg	1100	4
Die or Dies				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.038	mg	13935	57
Die or Dies				supplier	glass coating	Glass: Silicon Dioxide (SiO2)	7631-86-9		0.038	mg	13935	57
Leadframe	Copper & its alloys	204.692	mg	supplier	alloy	Copper (Cu)	7440-50-8		199.245	mg	973389	297381
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		4.686	mg	22893	6994
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.282	mg	1378	421
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.245	mg	1197	366
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.214	mg	1045	319
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.014	mg	68	21
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.006	mg	29	9
Die attach	Other inorganic materials	0.787	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.606	mg	770013	904
Die attach				supplier	glue or tape	Epoxy Cresol Novolak	29690-82-2		0.178	mg	226175	266
Die attach				supplier	glue or tape	1-isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.003	mg	3812	4
Bonding wire	Precious metals	0.541		supplier	wire	Gold (Au)	7440-57-5		0.541	mg	1000000	807
encapsulation	Other inorganic materials	461.253	mg	supplier	mold compound	Silica, vitreous	60676-86-0		369.001	mg	799997	550748
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		32.288	mg	70001	48191
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		18.450	mg	40000	27537
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		27.676	mg	60002	41307
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		5.535	mg	12000	8261
encapsulation				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		6.919	mg	15000	10327
encapsulation				supplier	mold compound	Carbon black	1333-86-4		1.384	mg	3001	2066